

Atty. Docket No. CPAC 1017-3  
Appl. No. 10/632,568

PATENT

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SEP 11 2006

Applicant: Marcos Karnozos )

) Examiner: Douglas M. Mcnz

Application No.: 10/632,568 )

) Group Art Unit: 2824

Filed: August 2, 2003 )

) Date: September 11, 2006.

Title: **Semiconductor multi-package module  
having package stacked over ball grid array  
package and having wire bond interconnect  
between stacked packages** )

) **CONFIRMATION NO. 2603**

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I hereby certify that this correspondence is being facsimile transmitted to  
Examiner Mcnz in the United States Patent and Trademark Office, at the Central  
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Signed

  
Bill Kennedy

COMMISSIONER FOR PATENTS  
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AMENDMENT

Dear Sir:

In response to the Office action mailed March 10, 2006, kindly amend the application as follows.

Amendments to the claims are reflected in the **Listing of Claims**, which begins on page 2 of this paper.

Remarks begin on page 6 of this paper.